

HVC306B

Variable Capacitance Diode for VHF tuner

HITACHI

ADE-208-612 (Z)

Rev 0

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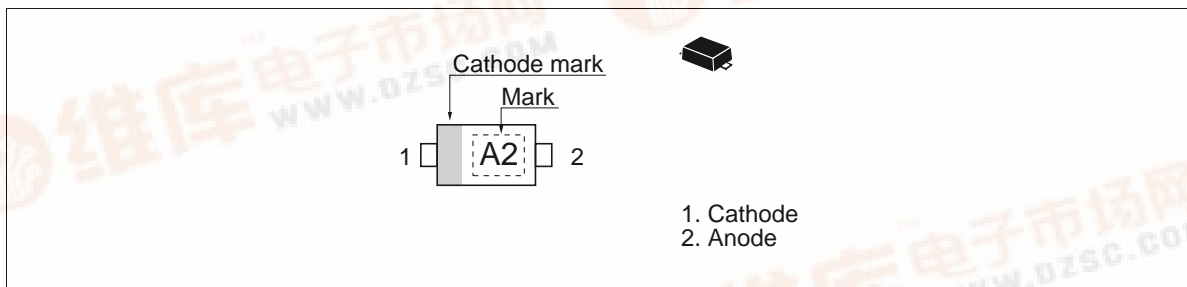
Features

- Low matching error. ($\Delta C/C = 2.0\%$ max)
- High capacitance ratio. ($n = 11.0$ min)
- Low series resistance. ($r_s = 0.75\Omega$ max)
- Ultra small Flat Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVC306B	A2	UFP

Outline



HVC306B

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Value	Unit
Peak reverse voltage	V_{RM}^{*1}	35	V
Reverse voltage	V_R	34	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Note 1. RL=10KΩ

Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	I_{R1}	—	—	10	nA	$V_R = 32V$
	I_{R2}	—	—	100		$V_R = 32V, Ta = 60°C$
Capacitance	C_2	29.5	—	33.5	pF	$V_R = 2V, f = 1MHz$
	C_{25}	2.60	—	2.90		$V_R = 25V, f = 1MHz$
Capacitance ratio	n	11.0	—	—	—	C_2/C_{25}
Series resistance	r_s	—	—	0.75	Ω	$V_R = 5V, f = 470MHz$
Matching error	$\Delta C/C^{*1}$	—	—	2.0	%	$V_R = 2 \text{ to } 25V, f = 1 \text{ MHz}$

Note 1. C.C system (Continuous Connected taping system) enable to make any 10 pcs of $\Delta C/C$ continuous in a reel, expect extention to another group.
Calculate Matching Error,

$$\Delta C/C = \frac{(C_{max} - C_{min})}{C_{min}} \times 100 (\%)$$

Main Characteristic

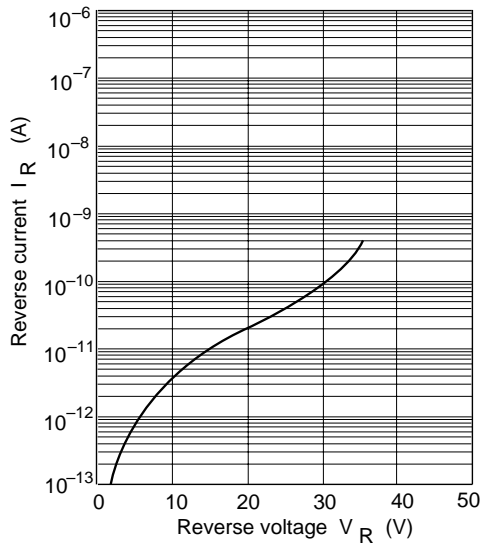


Fig.1 Reverse current Vs. Reverse voltage

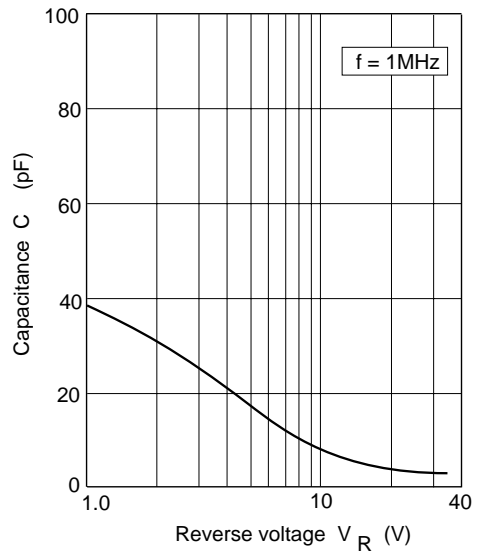


Fig.2 Capacitance Vs. Reverse voltage

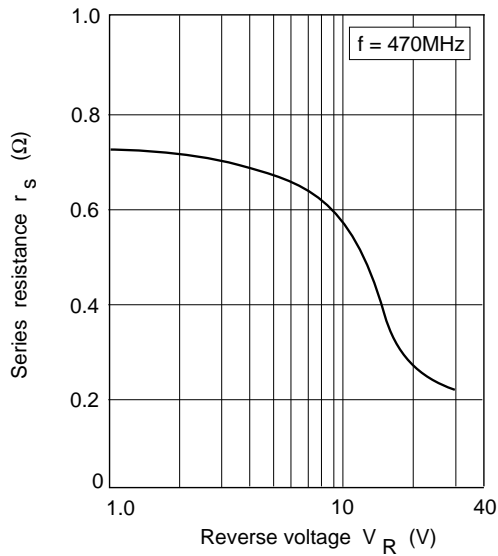


Fig.3 Series resistance Vs. Reverse voltage

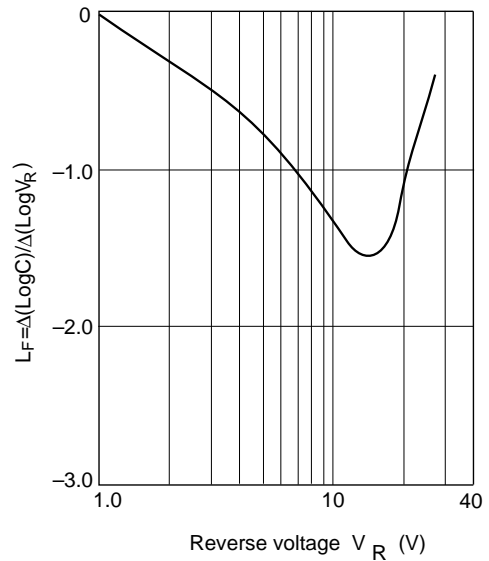
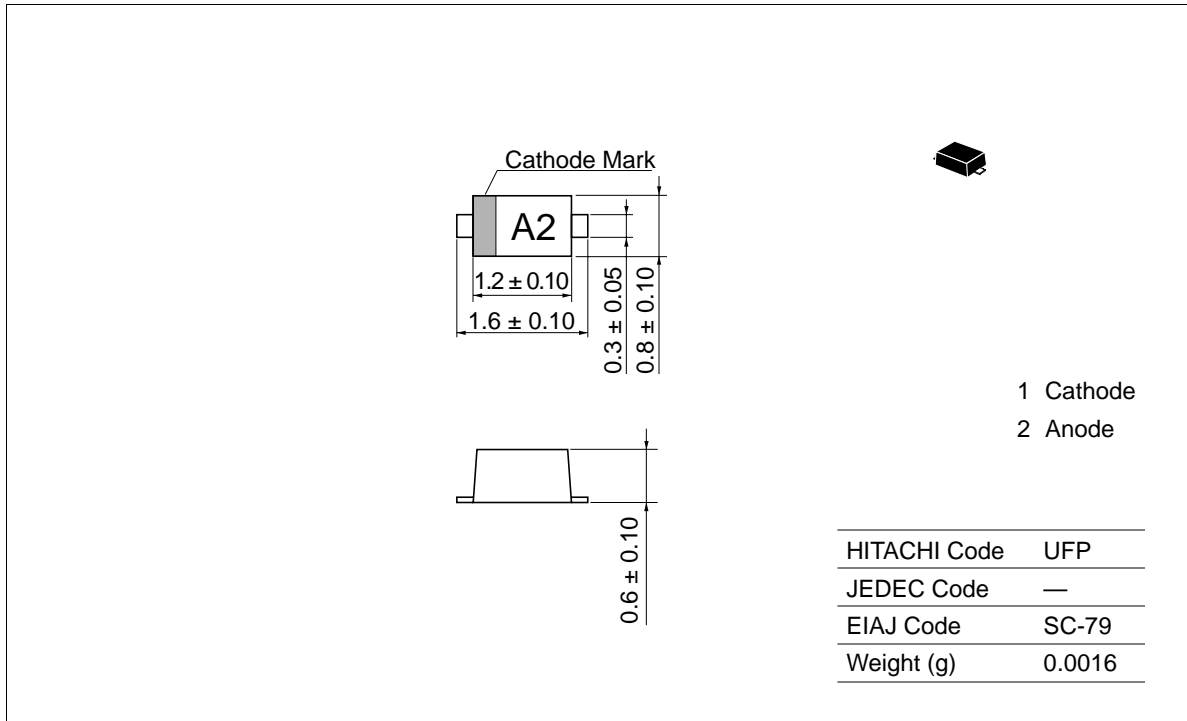


Fig.4 Linearity factor Vs. Reverse voltage

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Package Dimensions

Unit : mm



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HITACHI

Hitachi, Ltd.

Semiconductor & Integrated Circuits.
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL NorthAmerica : <http://semiconductor.hitachi.com/>
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For further information write to:

Hitachi Semiconductor
(America) Inc.
179 East Tasman Drive,
San Jose, CA 95134
Tel: <1> (408) 433-1990
Fax: <1> (408) 433-0223

Hitachi Europe GmbH
Electronic components Group
Dornacher StraÙe 3
D-85622 Feldkirchen, Munich
Germany
Tel: <49> (89) 9 9180-0
Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd.
Electronic Components Group.
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA, United Kingdom
Tel: <44> (1628) 585000
Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd.
16 Collyer Quay #20-00
Hitachi Tower
Singapore 049318
Tel: 535-2100
Fax: 535-1533

Hitachi Asia Ltd.
Taipei Branch Office
3F, Hung Kuo Building, No.167,
Tun-Hwa North Road, Taipei (105)
Tel: <886> (2) 2718-3666
Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower, World Finance Centre,
Harbour City, Canton Road, Tsim Sha Tsui,
Kowloon, Hong Kong
Tel: <852> (2) 735 9218
Fax: <852> (2) 730 0281
Telex: 40815 HITEC HX